

# 74AHC594-Q100; 74AHCT594-Q100

8-bit shift register with output register

Rev. 2 — 4 July 2013

Product data sheet

## 1. General description

The 74AHC594-Q100; 74AHCT594-Q100 is a high-speed Si-gate CMOS device and is pin compatible with Low-Power Schottky TTL (LSTTL). It is specified in compliance with JEDEC standard No. 7A.

The 74AHC594-Q100; 74AHCT594-Q100 is an 8-bit, non-inverting, serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. Separate clocks (SHCP and STCP) and direct overriding clears (SHR and STR) are provided on both the shift and storage registers. A serial output (Q7S) is provided for cascading purposes.

Both the shift and storage register clocks are positive-edge triggered. If the user wishes to connect both clocks together, the shift register is always one count pulse ahead of the storage register.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Balanced propagation delays
- All inputs have Schmitt trigger actions
- Inputs accept voltages higher than  $V_{CC}$
- Wide supply voltage range from 2.0 V to 5.5 V
- 8-bit serial-in, parallel-out shift register with storage
- Independent direct overriding clears on shift and storage registers
- Independent clocks for shift and storage registers
- Latch-up performance exceeds 100 mA per JESD78 Class II
- Input levels:
  - ◆ For 74AHC594-Q100: CMOS level
  - ◆ For 74AHCT594-Q100: TTL level
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V ( $C = 200\text{ pf}$ ,  $R = 0\text{ }\Omega$ )
- Multiple package options



### 3. Applications

- Serial-to parallel data conversion
- Remote control holding register

### 4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
<b>74AHC594-Q100</b>				
74AHC594D-Q100	–40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74AHC594DB-Q100	–40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74AHC594PW-Q100	–40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74AHC594BQ-Q100	–40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1
<b>74AHCT594-Q100</b>				
74AHCT594D-Q100	–40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74AHCT594DB-Q100	–40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74AHCT594PW-Q100	–40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74AHCT594BQ-Q100	–40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1

5. Functional diagram

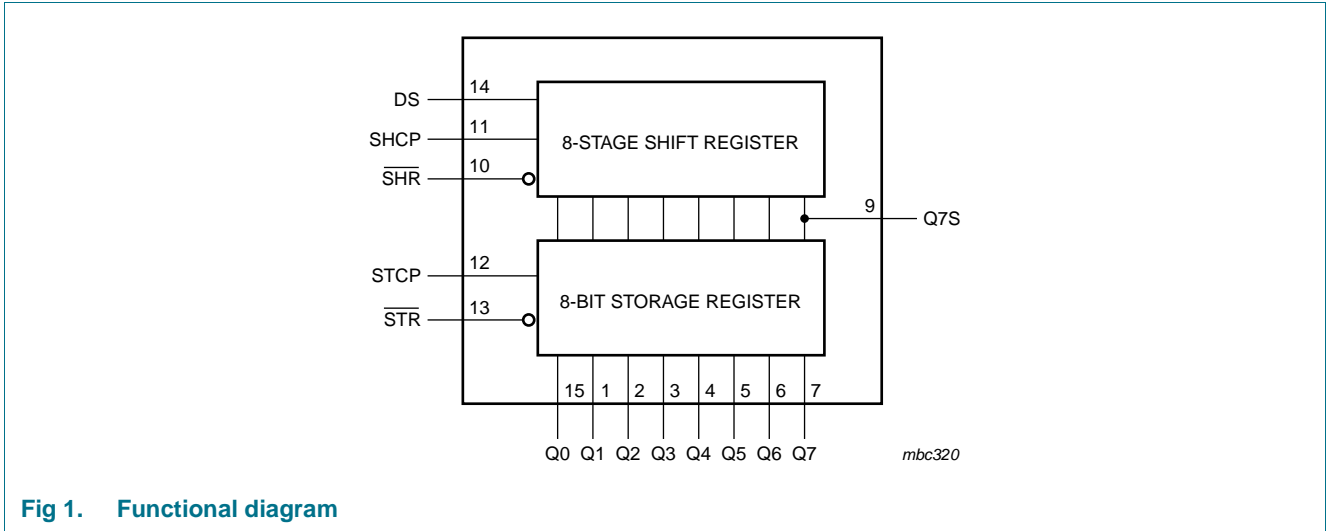


Fig 1. Functional diagram

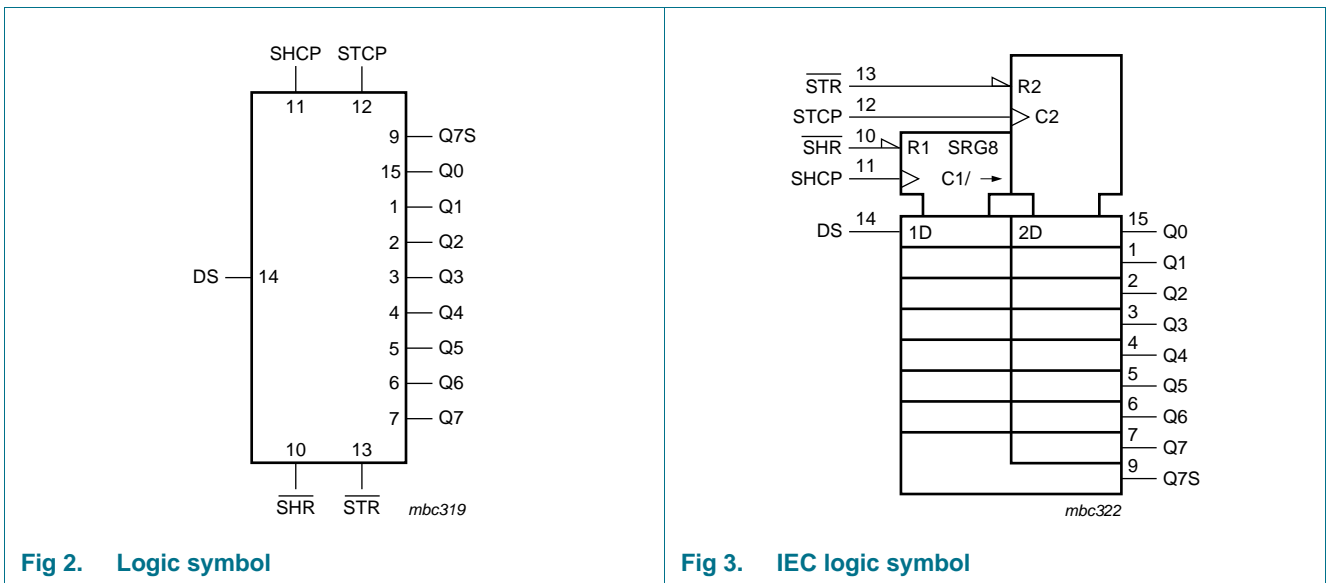


Fig 2. Logic symbol

Fig 3. IEC logic symbol

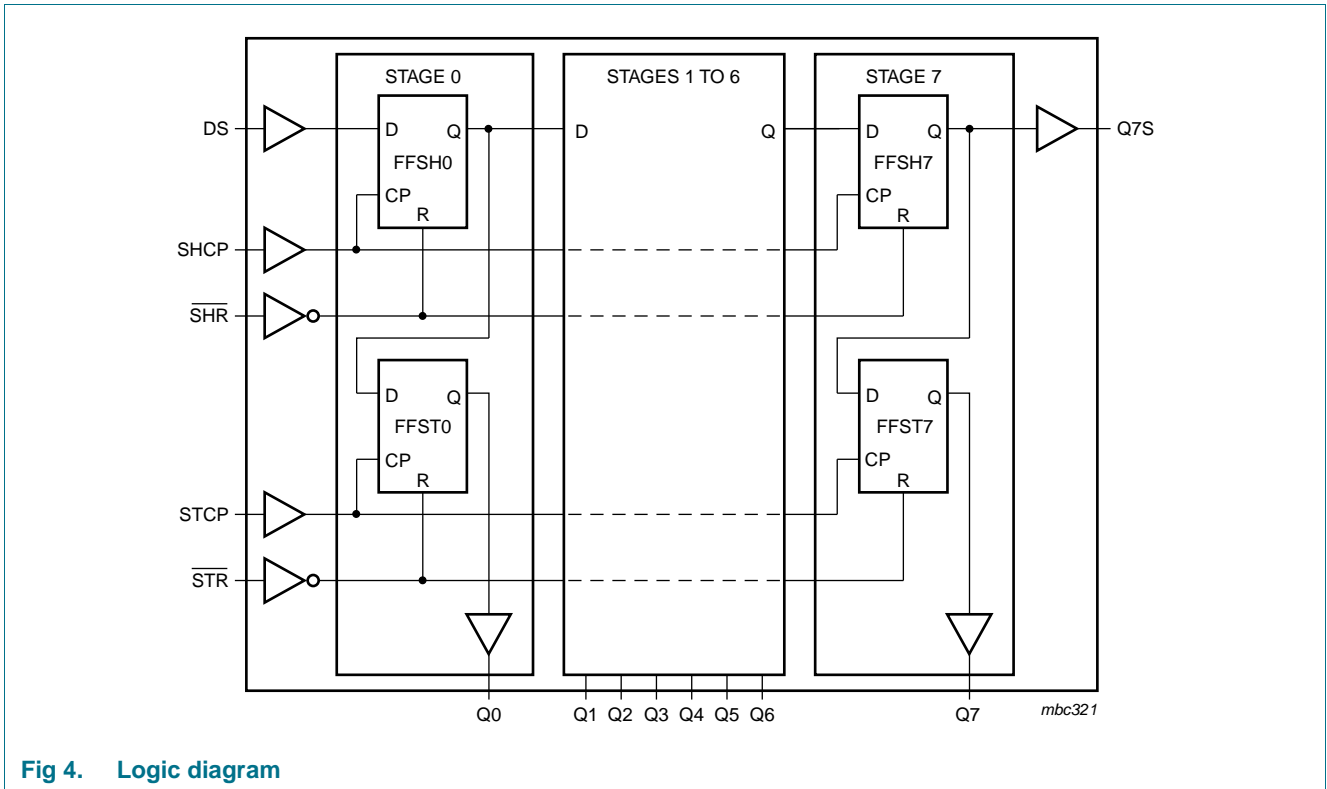


Fig 4. Logic diagram

## 6. Pinning information

### 6.1 Pinning

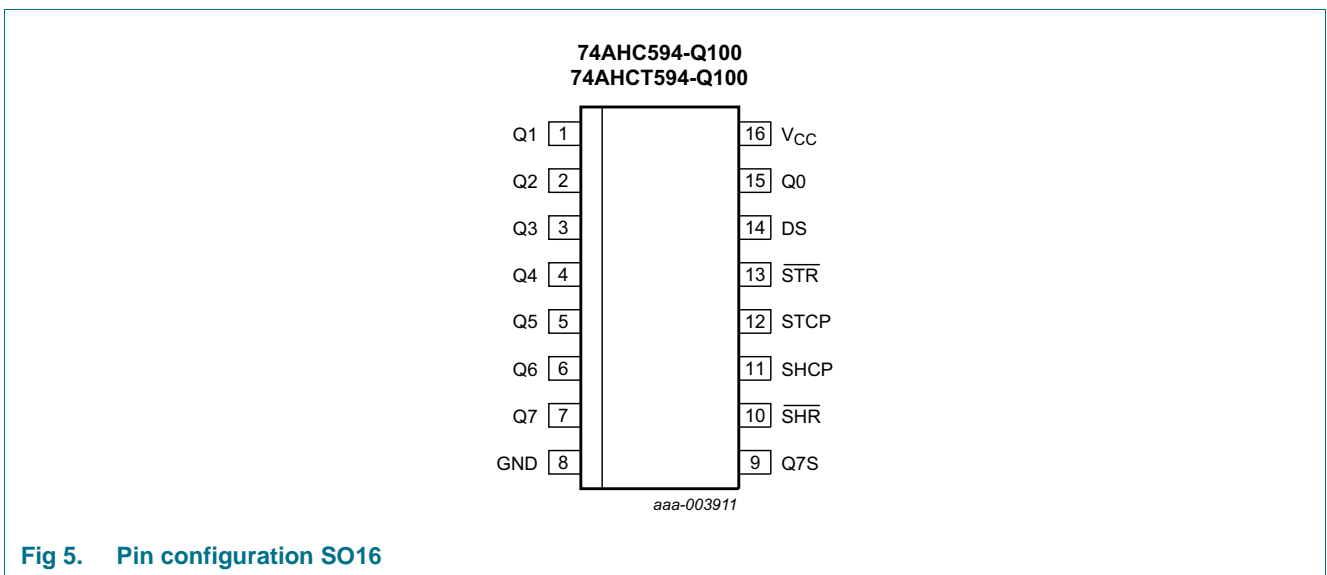


Fig 5. Pin configuration SO16

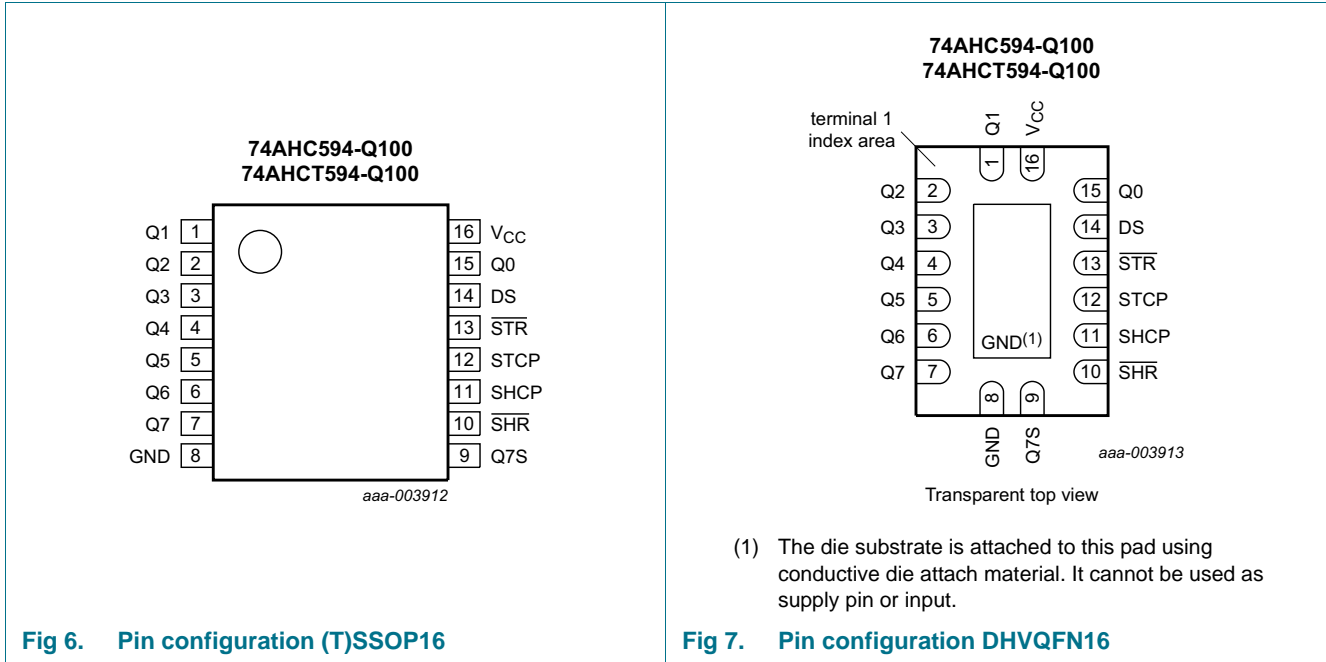


Fig 6. Pin configuration (T)SSOP16

Fig 7. Pin configuration DHVQFN16

6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
Q1	1	parallel data output
Q2	2	parallel data output
Q3	3	parallel data output
Q4	4	parallel data output
Q5	5	parallel data output
Q6	6	parallel data output
Q7	7	parallel data output
GND	8	ground (0 V)
Q7S	9	serial data output
SHR	10	shift register reset input (active LOW)
SHCP	11	shift register clock input
STCP	12	storage register clock input
STR	13	storage register reset input (active LOW)
DS	14	serial data input
Q0	15	parallel data output
V <sub>CC</sub>	16	supply voltage

## 7. Functional description

Table 3. Function table<sup>[1]</sup>

Input					Output		Function
SHCP	STCP	$\overline{\text{SHR}}$	$\overline{\text{STR}}$	DS	Q7S	Qn	
X	X	L	X	X	L	NC	a LOW-state on $\overline{\text{SHR}}$ only affects the shift register
X	X	X	L	X	NC	L	a LOW-state on $\overline{\text{STR}}$ only affects the storage register
X	↑	L	H	X	L	L	empty shift register loaded into storage register
↑	X	H	X	H	Q6S	NC	logic HIGH level shifted into shift register stage 0. Contents of all shift register stages shifted through, e.g. previous state of stage 6 (internal Q6S) appears on the serial output (Q7S).
X	↑	H	H	X	NC	QnS	contents of shift register stages (internal QnS) are transferred to the storage register and parallel output stages
↑	↑	H	H	X	Q6S	QnS	contents of shift register shifted through; previous contents of the shift register is transferred to the storage register and the parallel output stages

- [1] H = HIGH voltage state;  
 L = LOW voltage state;  
 ↑ = LOW to HIGH transition;  
 X = don't care;  
 NC = no change;

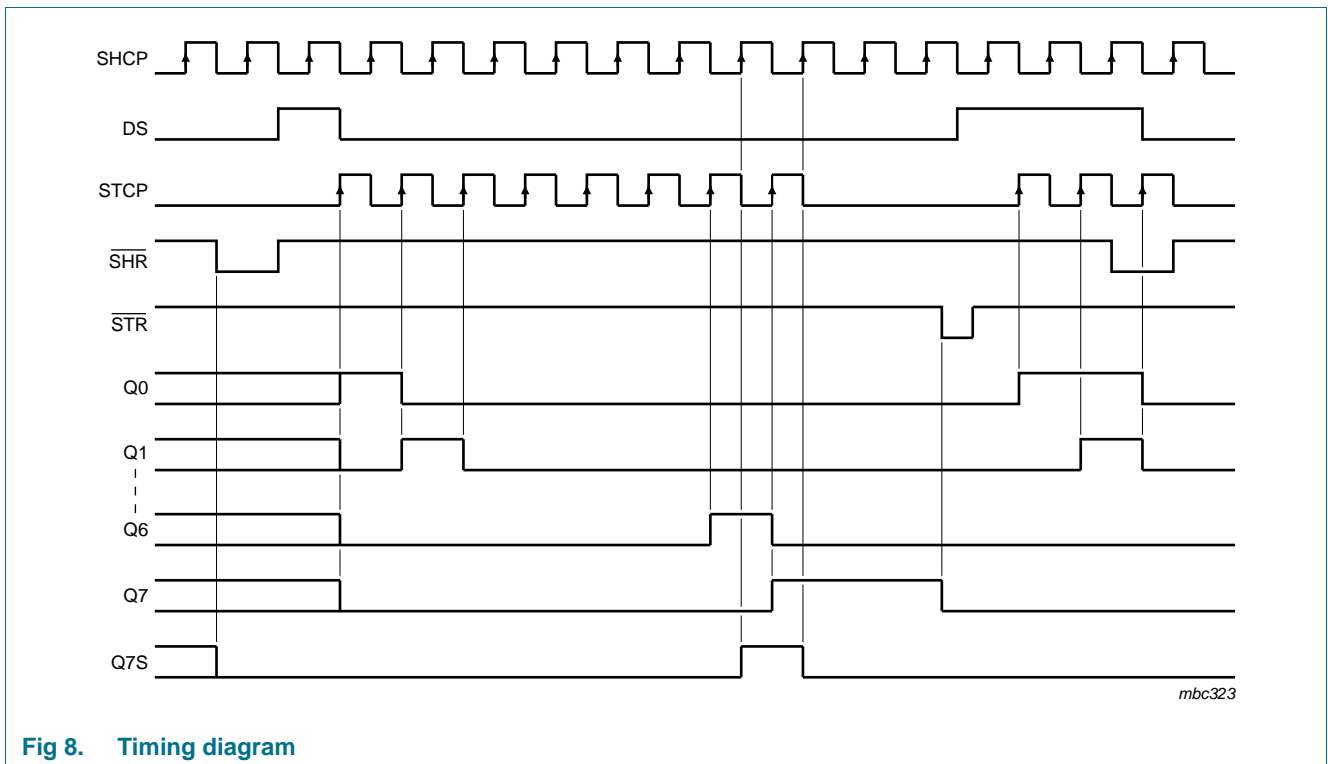


Fig 8. Timing diagram

## 8. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7.0	V
$V_I$	input voltage		-0.5	+7.0	V
$I_{IK}$	input clamping current	$V_I < -0.5$ V	[1] -20	-	mA
$I_{OK}$	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V	[1] -20	+20	mA
$I_O$	output current	$V_O = -0.5$ V to $(V_{CC} + 0.5$ V)	-25	+25	mA
$I_{CC}$	supply current		-	+75	mA
$I_{GND}$	ground current		-75	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to $+125$ °C	[2] -	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO16 packages: above 70 °C the value of  $P_{tot}$  derates linearly at 8 mW/K.

For (T)SSOP16 packages: above 60 °C the value of  $P_{tot}$  derates linearly at 5.5 mW/K.

For DHVQFN16 packages: above 60 °C the value of  $P_{tot}$  derates linearly at 4.5 mW/K.

## 9. Recommended operating conditions

Table 5. Operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>74AHC594-Q100</b>						
$V_{CC}$	supply voltage		2.0	5.0	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	-	-	100	ns/V
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-	-	20	ns/V
<b>74AHCT594-Q100</b>						
$V_{CC}$	supply voltage		4.5	5.0	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-	-	20	ns/V

## 10. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74AHC594-Q100</b>										
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 2.0\text{ V}$	1.5	-	-	1.5	-	1.5	-	V
		$V_{CC} = 3.0\text{ V}$	2.1	-	-	2.1	-	2.1	-	V
		$V_{CC} = 5.5\text{ V}$	3.85	-	-	3.85	-	3.85	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 2.0\text{ V}$	-	-	0.5	-	0.5	-	0.5	V
		$V_{CC} = 3.0\text{ V}$	-	-	0.9	-	0.9	-	0.9	V
		$V_{CC} = 5.5\text{ V}$	-	-	1.65	-	1.65	-	1.65	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = -50\ \mu\text{A}; V_{CC} = 2.0\text{ V}$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -50\ \mu\text{A}; V_{CC} = 3.0\text{ V}$	2.9	3.0	-	2.9	-	2.9	-	V
		$I_O = -50\ \mu\text{A}; V_{CC} = 4.5\text{ V}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -4.0\text{ mA}; V_{CC} = 3.0\text{ V}$	2.58	-	-	2.48	-	2.40	-	V
	$I_O = -8.0\text{ mA}; V_{CC} = 4.5\text{ V}$	3.94	-	-	3.80	-	3.70	-	V	
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = 50\ \mu\text{A}; V_{CC} = 2.0\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 50\ \mu\text{A}; V_{CC} = 3.0\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 50\ \mu\text{A}; V_{CC} = 4.5\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 4\text{ mA}; V_{CC} = 3.0\text{ V}$	-	-	0.36	-	0.44	-	0.55	V
	$I_O = 8\text{ mA}; V_{CC} = 4.5\text{ V}$	-	-	0.36	-	0.44	-	0.55	V	



**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
I <sub>I</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	4.0	-	40	-	80	μA
C <sub>I</sub>	input capacitance	V <sub>I</sub> = V <sub>CC</sub> or GND	-	3	10	-	10	-	10	pF
<b>74AHCT594-Q100</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	-	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	-	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -8.0 mA; V <sub>CC</sub> = 4.5 V	3.94	-	-	3.80	-	3.70	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 8 mA; V <sub>CC</sub> = 4.5 V	-	-	0.36	-	0.44	-	0.55	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	4.0	-	40	-	80	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; other pins at V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 4.5 V to 5.5 V	-	-	1.35	-	1.5	-	1.5	mA
C <sub>I</sub>	input capacitance	V <sub>I</sub> = V <sub>CC</sub> or GND	-	3	10	-	10	-	10	pF

## 11. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 15](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	Min	Max	
<b>74AHC594-Q100</b>										
t <sub>PLH</sub>	LOW to HIGH propagation delay	SHCP to Q7S; see <a href="#">Figure 9</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	5.2	8.5	2.2	9.7	2.2	10.6	ns
		C <sub>L</sub> = 50 pF	-	7.4	11.5	3.0	13.2	3.0	14.3	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	3.8	6.3	1.7	7.2	1.7	7.8	ns
		C <sub>L</sub> = 50 pF	-	4.8	8.0	2.4	9.1	2.4	10.0	ns

**Table 7. Dynamic characteristics ...continued**

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 15](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	Min	Max	
t <sub>PHL</sub>	HIGH to LOW propagation delay	STCP to Qn; see <a href="#">Figure 10</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	5.1	8.3	2.3	9.5	2.3	10.6	ns
		C <sub>L</sub> = 50 pF	-	7.3	11.9	3.3	13.6	3.3	14.7	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	3.5	5.7	1.8	6.5	1.8	7.1	ns
		C <sub>L</sub> = 50 pF	-	4.8	7.8	2.6	9.0	2.6	9.8	ns
		SHCP to Q7S; see <a href="#">Figure 9</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	5.5	8.9	2.3	10.2	2.3	11.0	ns
		C <sub>L</sub> = 50 pF	-	7.4	12.1	3.0	13.9	3.0	15.1	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	4.1	6.7	1.9	7.6	1.9	8.2	ns
		C <sub>L</sub> = 50 pF	-	5.4	8.8	2.5	10.1	2.5	11.0	ns
		STCP to Qn; see <a href="#">Figure 10</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	5.5	9.1	2.4	10.4	2.4	11.3	ns
		C <sub>L</sub> = 50 pF	-	7.3	12.0	3.2	13.8	3.2	15.0	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	3.7	6.0	1.9	6.9	1.9	7.5	ns
C <sub>L</sub> = 50 pF	-	5.2	8.5	2.6	9.7	2.6	10.5	ns		
SHR to Q7S; see <a href="#">Figure 13</a>										
V <sub>CC</sub> = 3.0 V to 3.6 V										
C <sub>L</sub> = 15 pF	-	5.7	9.5	2.3	10.8	2.3	11.7	ns		
C <sub>L</sub> = 50 pF	-	7.5	12.2	3.6	14.0	3.6	15.2	ns		
V <sub>CC</sub> = 4.5 V to 5.5 V										
C <sub>L</sub> = 15 pF	-	4.1	6.7	2.0	7.6	2.0	8.2	ns		
C <sub>L</sub> = 50 pF	-	5.4	8.8	2.8	10.1	2.8	11.0	ns		
STR to Qn; see <a href="#">Figure 14</a>										
V <sub>CC</sub> = 3.0 V to 3.6 V										
C <sub>L</sub> = 15 pF	-	5.8	9.6	2.8	11.0	2.8	12.0	ns		
C <sub>L</sub> = 50 pF	-	7.7	12.5	3.8	14.4	3.8	15.6	ns		
V <sub>CC</sub> = 4.5 V to 5.5 V										
C <sub>L</sub> = 15 pF	-	4.1	7.2	2.2	8.2	2.2	8.9	ns		
C <sub>L</sub> = 50 pF	-	5.4	9.4	3.0	10.7	3.0	11.6	ns		
f <sub>max</sub>	maximum frequency	SHCP or STCP; see <a href="#">Figure 9</a> and <a href="#">Figure 10</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V	80	125	-	70	-	65	-	MHz
		V <sub>CC</sub> = 4.5 V to 5.5 V	90	170	-	80	-	70	-	MHz

**Table 7. Dynamic characteristics ...continued**

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 15](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	Min	Max	
t <sub>w</sub>	pulse width	SHCP and STCP HIGH or LOW; see <a href="#">Figure 9</a> and <a href="#">Figure 10</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V	6.0	-	-	6.5	-	7.0	-	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	5.5	-	-	6.0	-	6.5	-	ns
		SHR and STR HIGH or LOW; see <a href="#">Figure 13</a> and <a href="#">Figure 14</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V	5.0	-	-	5.0	-	5.5	-	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	5.0	-	-	5.2	-	5.7	-	ns
t <sub>su</sub>	set-up time	DS to SHCP; see <a href="#">Figure 11</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V	3.5	-	-	3.5	-	4.0	-	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	3.0	-	-	3.0	-	3.5	-	ns
		SHR to STCP; see <a href="#">Figure 12</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V	8.0	-	-	9.0	-	9.5	-	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	5.0	-	-	5.0	-	5.5	-	ns
		SHCP to STCP; see <a href="#">Figure 10</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V	8.0	-	-	8.5	-	9.0	-	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	5.0	-	-	5.0	-	5.5	-	ns
t <sub>h</sub>	hold time	DS to SHCP; see <a href="#">Figure 11</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.5	-	-	1.5	-	2.0	-	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	-	-	2.0	-	2.5	-	ns
t <sub>rec</sub>	recovery time	SHR to SHCP; see <a href="#">Figure 13</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V	4.2	-	-	4.8	-	5.3	-	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	2.9	-	-	3.3	-	3.8	-	ns
		STR to STCP; see <a href="#">Figure 14</a>								
		V <sub>CC</sub> = 3.0 V to 3.6 V	4.6	-	-	5.3	-	5.8	-	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	3.2	-	-	3.7	-	4.3	-	ns
C <sub>PD</sub>	power dissipation capacitance	f <sub>i</sub> = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[2]</sup>	-	55	-	-	-	-	-	pF

**74AHCT594-Q100; V<sub>CC</sub> = 4.5 V to 5.5 V**

t <sub>PLH</sub>	LOW to HIGH propagation delay	SHCP to Q7S; see <a href="#">Figure 9</a>								
		C <sub>L</sub> = 15 pF	-	3.8	6.3	1.7	7.2	1.7	7.8	ns
		C <sub>L</sub> = 50 pF	-	4.8	8.0	2.2	9.1	2.2	9.9	ns
		STCP to Qn; see <a href="#">Figure 10</a>								
		C <sub>L</sub> = 15 pF	-	3.5	5.7	1.8	6.5	1.8	7.1	ns
		C <sub>L</sub> = 50 pF	-	4.6	7.7	2.6	8.8	2.6	9.6	ns

**Table 7. Dynamic characteristics ...continued**

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 15](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	Min	Max	
t <sub>PHL</sub>	HIGH to LOW propagation delay	SHCP to Q7S; see <a href="#">Figure 9</a>								
		C <sub>L</sub> = 15 pF	-	4.1	6.7	1.8	7.6	1.8	8.3	ns
		C <sub>L</sub> = 50 pF	-	5.4	8.8	2.4	10.1	2.4	11.0	ns
		STCP to Qn; see <a href="#">Figure 10</a>								
		C <sub>L</sub> = 15 pF	-	3.7	6.1	1.9	6.9	1.9	7.2	ns
		C <sub>L</sub> = 50 pF	-	5.2	8.5	2.6	9.7	2.6	10.5	ns
		SHR to Q7S; see <a href="#">Figure 13</a>								
		C <sub>L</sub> = 15 pF	-	4.3	7.0	2.4	8.0	2.4	8.7	ns
		C <sub>L</sub> = 50 pF	-	5.4	8.8	2.7	10.1	2.7	11.0	ns
t <sub>max</sub>	maximum frequency	STR to Qn; see <a href="#">Figure 14</a>								
		C <sub>L</sub> = 15 pF	-	4.5	7.4	2.3	8.4	2.3	9.2	ns
		C <sub>L</sub> = 50 pF	-	5.7	9.4	3.1	10.7	3.1	11.7	ns
t <sub>W</sub>	pulse width	SHCP or STCP; see <a href="#">Figure 9</a> and <a href="#">Figure 10</a>	90	160	-	80	-	70	-	MHz
		SHCP and STCP HIGH or LOW; see <a href="#">Figure 9</a> and <a href="#">Figure 10</a>	5.5	-	-	6.0	-	6.5	-	ns
t <sub>su</sub>	set-up time	SHR and STR HIGH or LOW; see <a href="#">Figure 13</a> and <a href="#">Figure 14</a>	5.2	-	-	5.5	-	6.0	-	ns
		DS to SHCP; see <a href="#">Figure 11</a>	3.0	-	-	3.0	-	3.5	-	ns
		SHR to STCP; see <a href="#">Figure 12</a>	5.0	-	-	5.0	-	5.5	-	ns
t <sub>h</sub>	hold time	SHCP to STCP; see <a href="#">Figure 10</a>	5.0	-	-	5.0	-	5.5	-	ns
		DS to SHCP; see <a href="#">Figure 11</a>	2.0	-	-	2.0	-	2.5	-	ns
t <sub>rec</sub>	recovery time	SHR to SHCP; see <a href="#">Figure 13</a>	2.9	-	-	3.3	-	3.8	-	ns
		STR to STCP; see <a href="#">Figure 14</a>	3.4	-	-	3.8	-	4.3	-	ns
C <sub>PD</sub>	power dissipation capacitance	f <sub>i</sub> = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[2]</sup>	-	55	-	-	-	-	-	pF

[1] Typical values are measured at nominal supply voltage (V<sub>CC</sub> = 3.3 V and V<sub>CC</sub> = 5.0 V).

[2] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

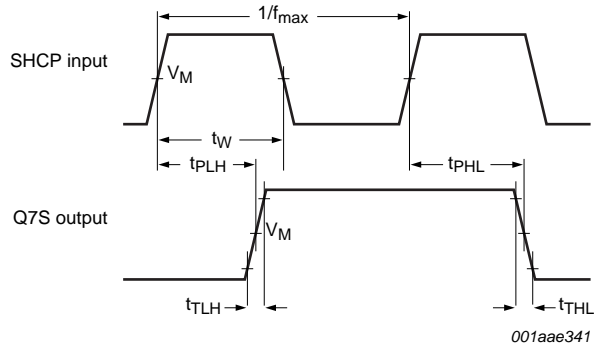
C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

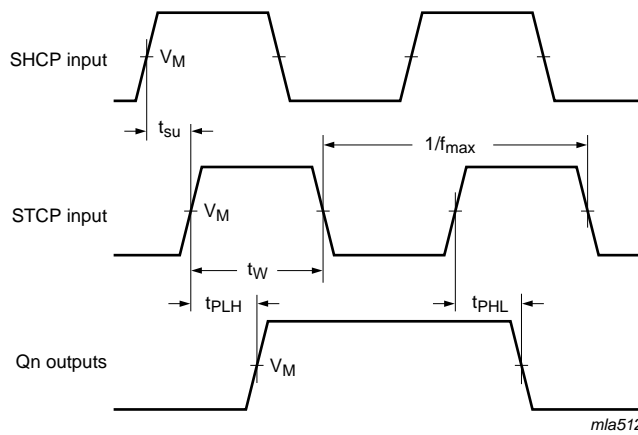
Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of the outputs.

12. Waveforms



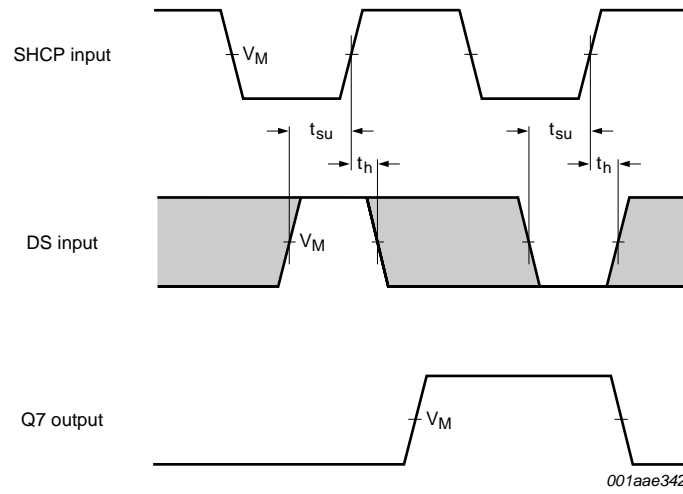
Measurement points are given in [Table 8](#).

Fig 9. Shift register clock pulse width, maximum frequency and input to output propagation delays



Measurement points are given in [Table 8](#).

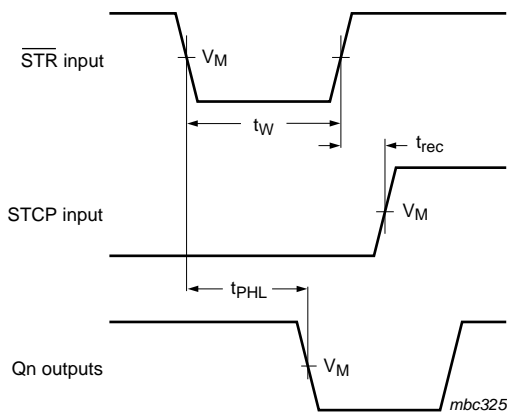
Fig 10. Shift register clock to storage register clock set-up time and storage clock pulse width, maximum frequency and input to output propagation delays



Measurement points are given in [Table 8](#).

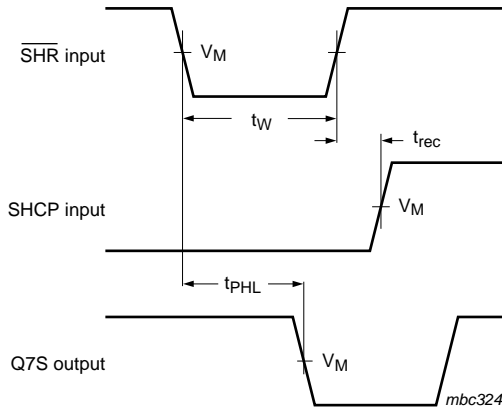
The shaded areas indicate when the input is permitted to change for predictable output performance.

**Fig 11. Shift register clock to data input set-up and hold times**



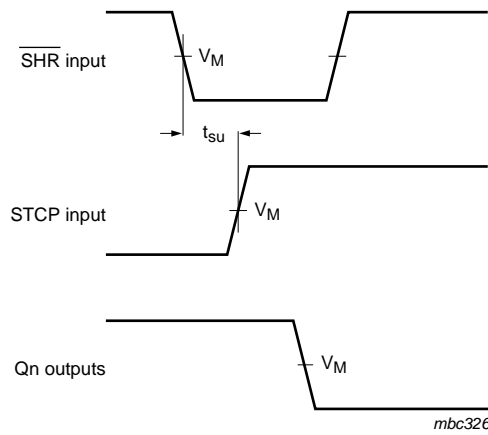
Measurement points are given in [Table 8](#).

**Fig 12. Storage register reset pulse width, input to output propagation delay and recovery time**



Measurement points are given in [Table 8](#).

**Fig 13. Shift register reset pulse width, input to output propagation delay and recovery time**

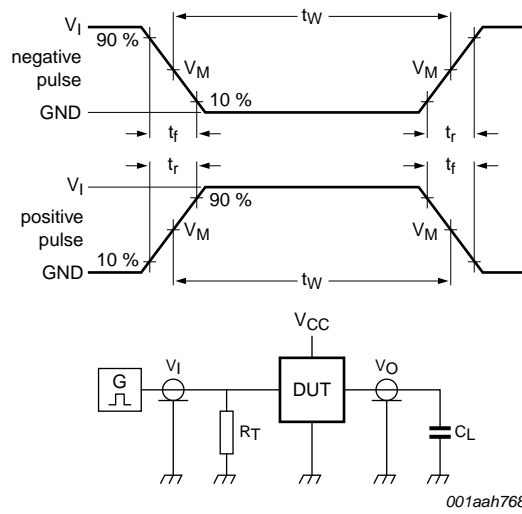


Measurement points are given in [Table 8](#).

**Fig 14. Shift register reset to storage register clock set-up time**

**Table 8. Measurement points**

Type	Input	Output
	$V_M$	$V_M$
74AHC594-Q100	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
74AHCT594-Q100	1.5 V	$0.5 \times V_{CC}$



For test data, see [Table 9](#).

Definitions for test circuit:

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = Load capacitance including jig and probe capacitance.

**Fig 15. Load circuitry for measuring switching times**

**Table 9. Test data**

Type	Input		Load	Test
	$V_I$	$t_r, t_f$	$C_L$	
74AHC594-Q100	$V_{CC}$	$\leq 3.0$ ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$
74AHCT594-Q100	3.0 V	$\leq 3.0$ ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$



13. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

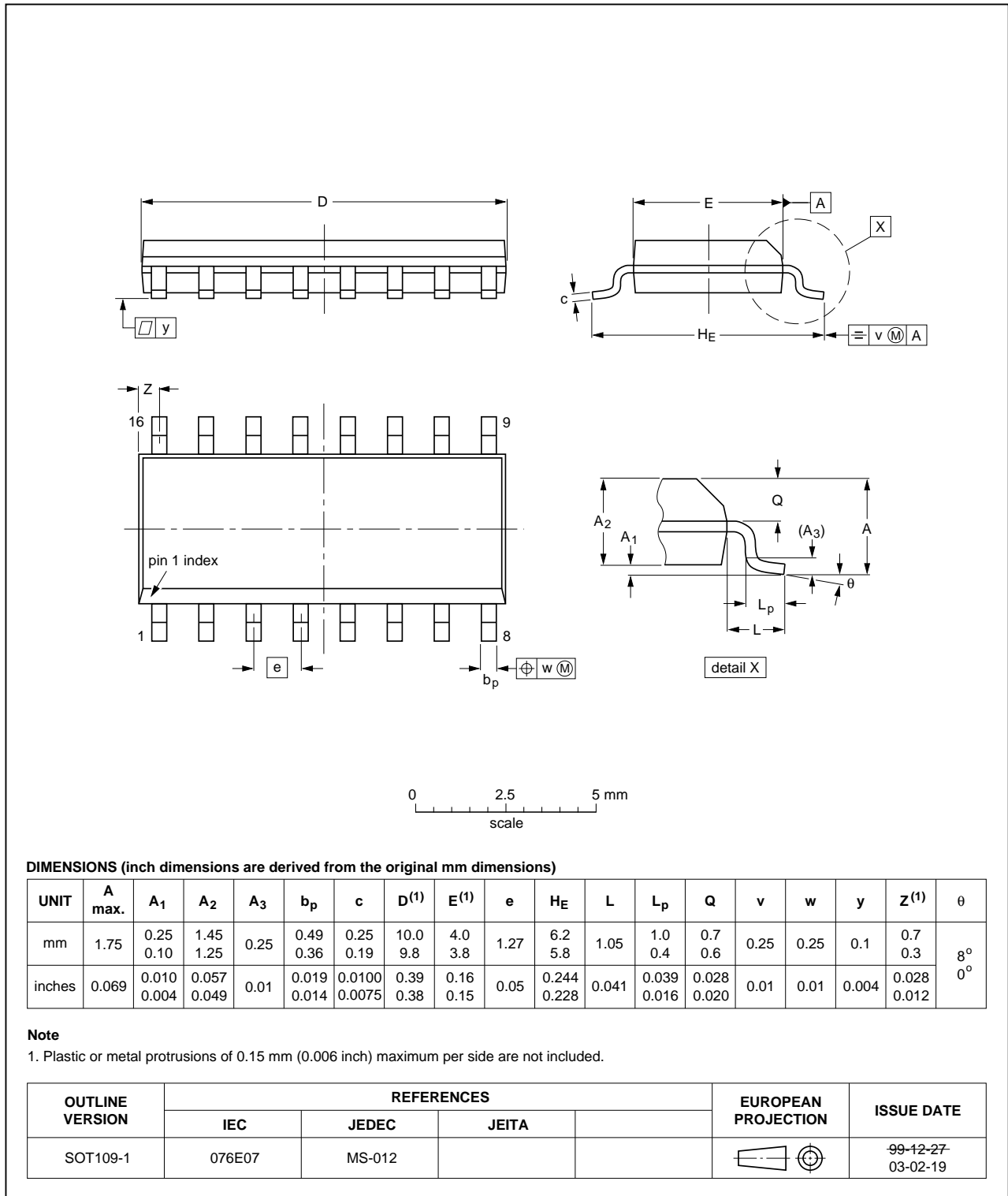


Fig 16. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

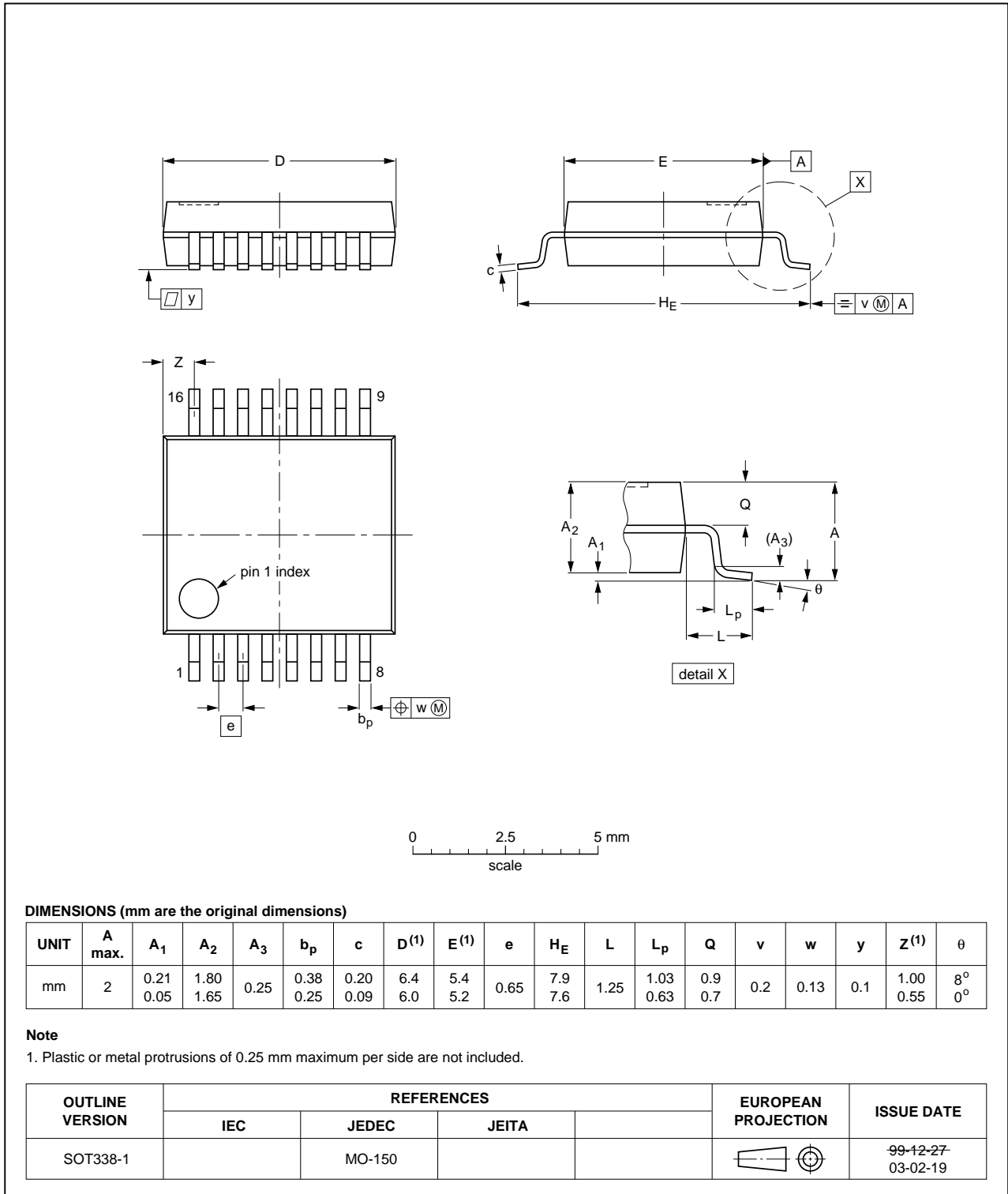


Fig 17. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

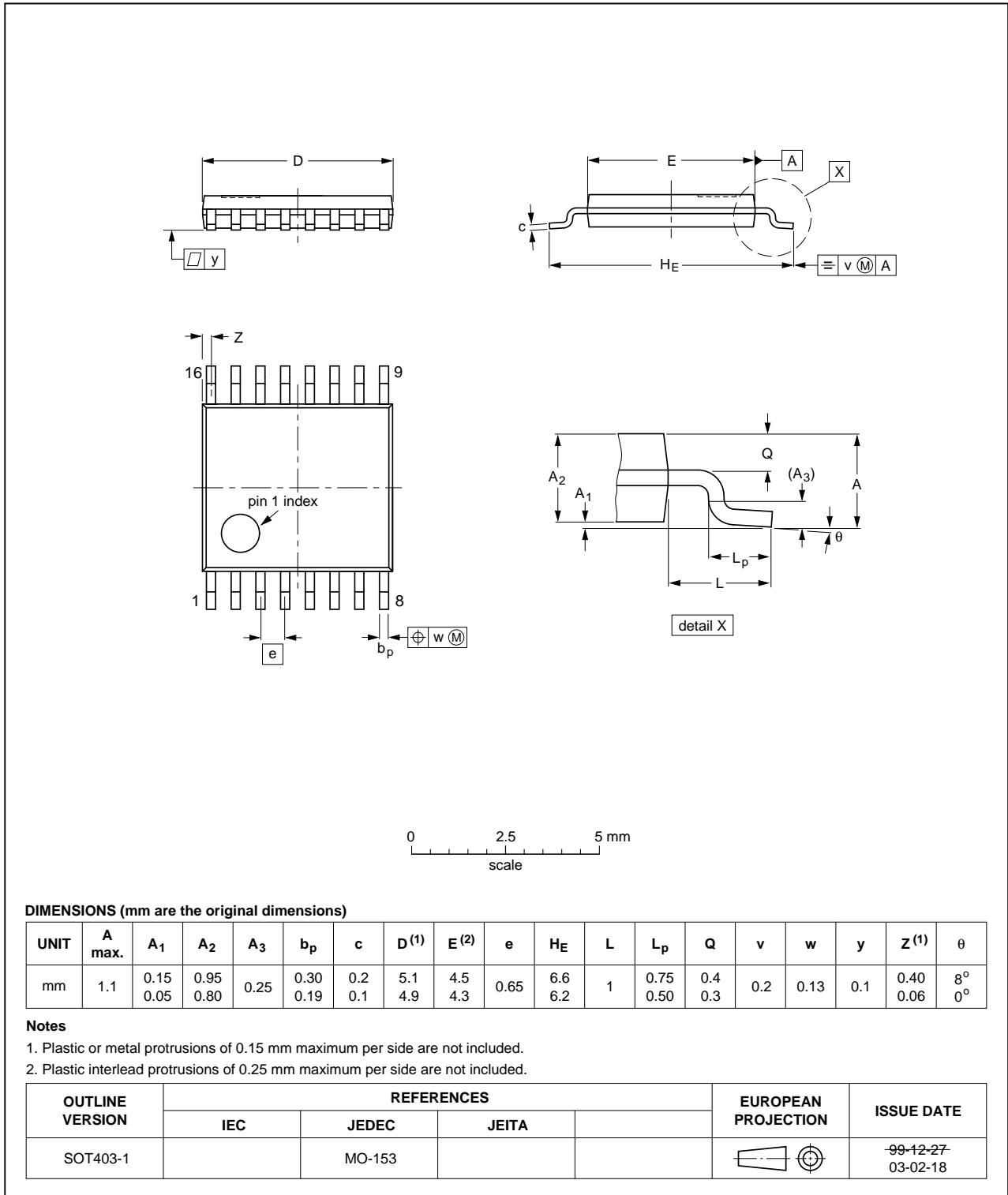


Fig 18. Package outline SOT403-1 (TSSOP16)

DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm

SOT763-1

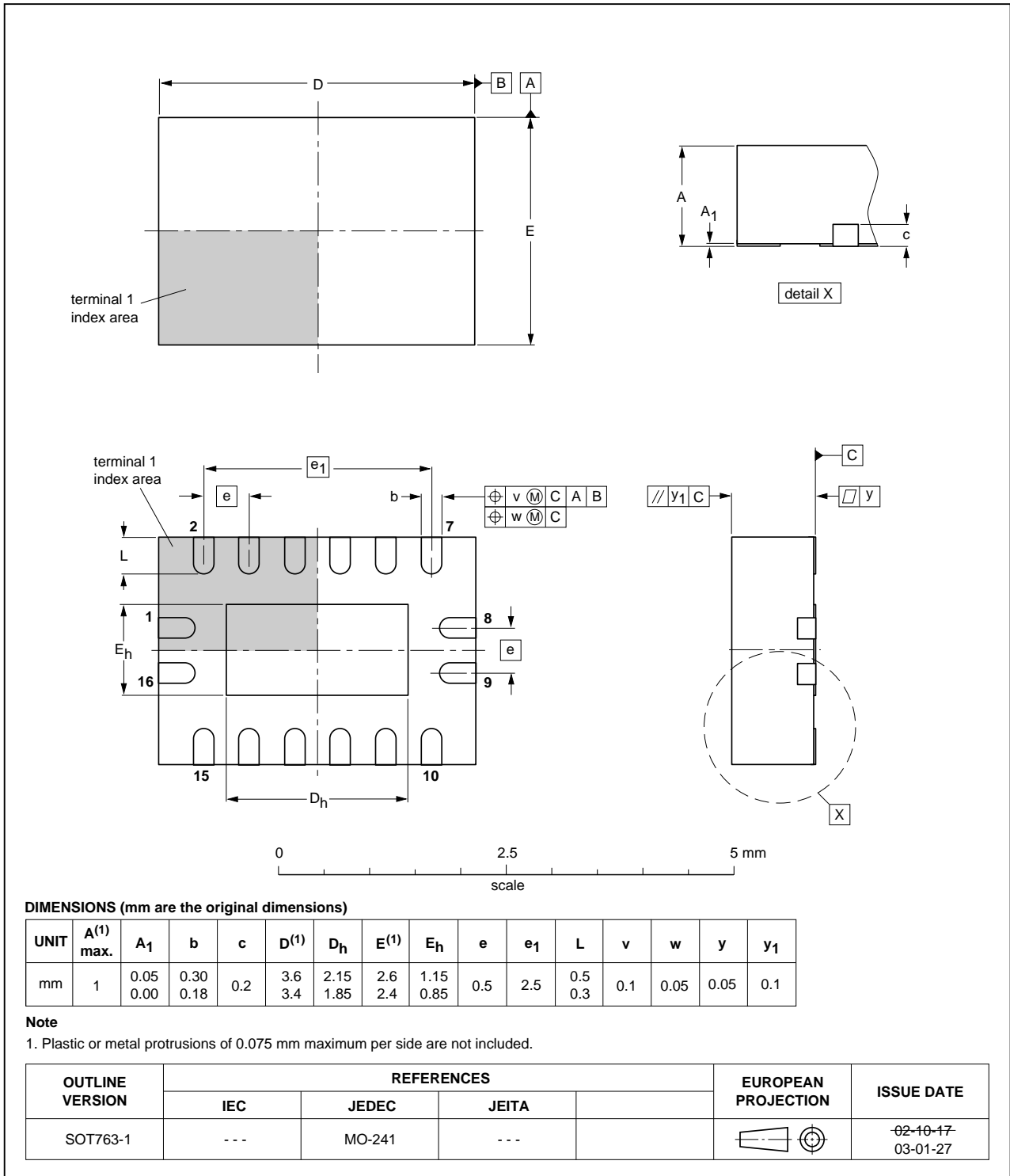


Fig 19. Package outline SOT763-1 (DHVQFN16)

## 14. Abbreviations

**Table 10. Abbreviations**

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
LSTTL	Low-power Schottky Transistor-Transistor Logic
MM	Machine Model
MIL	Military

## 15. Revision history

**Table 11. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC_AHCT594_Q100 v.2	20130704	Product data sheet	-	74AHC_AHCT594_Q100 v.1
Modifications:	<ul style="list-style-type: none"> <li>74AHC594DB-Q100 and 74AHCT594DB-Q100 added.</li> </ul>			
74AHC_AHCT594_Q100 v.1	20120712	Product data sheet	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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